Reliability testing starts with reliable sockets

PRODUCT DESCRIPTION
Plastronics introduces a new family of sockets that use Single Beam contact technology to serve ball grid array applications from 1.0mm to 0.4mm pitch.

Single Beam contact technology is a patented innovation that is inherently less expensive to produce.

Sockets with Single Beam contact technology provide more flexibility with larger array size and smaller socket footprints.

APPLICATION NOTES
More flexibility and less cost throughout the life cycle of the Single Beam socket:
- Less complex and more precise tooling
- Socket footprint - increase board utilization
- Slider-carrier - less contact stress loads
- More robust - increase socket life

MECHANICAL PROPERTIES
- Contact: Single Beam/Stationary
- Mounting: Thru hole
- Insertion: ZIF
- Contact Force: 15 ± 4gf
- Operating Temperature: -45°C to +150°C
- Load Cycles: 10,000 (burn-in) 50,000 (programming)

ELECTRICAL PROPERTIES
- Contact Resistance: < 50 mOhms
- Inductance: < 6 nH
- Capacitance: < 2.59 pF
- Current Rating: 1 amp
- Volume Resistivity: 1,000 MOhm @ 100 VDC
- Insulation Resistance: 100 VAC for 1 minute

Patent No: US7, 025, 602

H-Pin is a registered trademark of Plastronics

Call us: 972-258-2580 | Email us: sales@plastronics.com

www.plastronics.com
SOCKET SIZE: 17mm X 28mm
MAXIMUM IC SIZE: 12mm X 22mm
MAXIMUM BALL ARRAY: 13 X 21

CONTACT DETAILS

1) Initial
   - Slider Movement—Left
   - Contact Stationary

2) Open (Cover Down)
   - Slider & IC Movement—Right
   - Contact Stationary

3) Closed (After IC Loading)
   - Initial Contact
   - Fully Contacted